imall

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Tel: +86-755-8981 8866 Fax: +86-755-8427 6832 Email & Skype: info@chipsmall.com Web: www.chipsmall.com Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China





3.3V ZERO DELAY CLOCK BUFFER

IDT2305

FEATURES:

- Phase-Lock Loop Clock Distribution
- 10MHz to 133MHz operating frequency
- · Distributes one clock input to one bank of five outputs
- Zero Input-Output Delay
- Output Skew < 250ps
- Low jitter <200 ps cycle-to-cycle
- IDT2305-1 for Standard Drive
- IDT2305-1H for High Drive
- No external RC network required
- Operates at 3.3V VDD
- Power down mode
- Available in SOIC/TSSOP packages

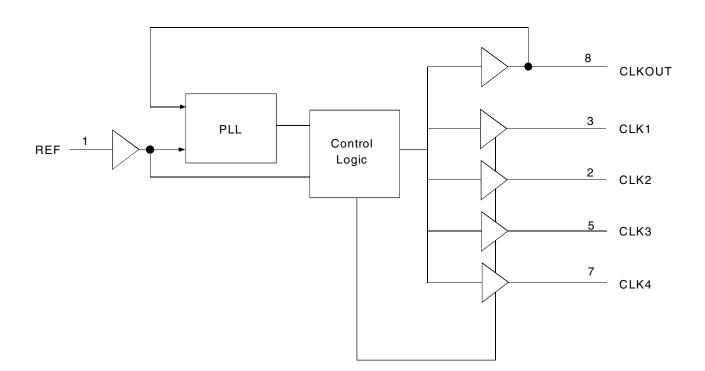
DESCRIPTION:

The IDT2305 is a high-speed phase-lock loop (PLL) clock buffer, designed to address high-speed clock distribution applications. The zero delay is achieved by aligning the phase between the incoming clock and the output clock, operable within the range of 10 to 133MHz.

The IDT2305 is an 8-pin version of the IDT2309. IDT2305 accepts one reference input, and drives out five low skew clocks. The -1H version of this device operates, up to 133MHz frequency and has a higher drive than the -1 device. All parts have on-chip PLLs which lock to an input clock on the REF pin. The PLL feedback is on-chip and is obtained from the CLKOUT pad. In the absence of an input clock, the IDT2305 enters power down. In this mode, the device will draw less than 25μ A, the outputs are tri-stated, and the PLL is not running, resulting in a significant reduction of power.

The IDT2305 is characterized for both Industrial and Commercial operation.

FUNCTIONAL BLOCK DIAGRAM



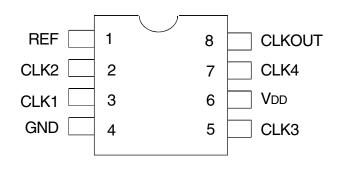
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COMMERCIAL AND INDUSTRIAL TEMPERATURE RANGES

AUGUST 2012

PINCONFIGURATION



SOIC/TSSOP TOP VIEW

ABSOLUTE MAXIMUM RATINGS⁽¹⁾

Symbol	Rating	Max.	Unit
Vdd	Supply Voltage Range	-0.5 to +4.6	V
VI ⁽²⁾	Input Voltage Range (REF)	-0.5 to +5.5	V
VI	Input Voltage Range	-0.5 to	V
	(except REF)	VDD+0.5	
Iк (VI < 0)	Input Clamp Current	50	mA
IO (VO = 0 to VDD)	Continuous Output Current	±50	mA
VDD or GND	Continuous Current	±100	mA
TA = 55°C	Maximum Power Dissipation	0.7	W
(in still air) ⁽³⁾			
Тѕтс	Storage Temperature Range	-65 to +150	°C
Operating	CommercialTemperature	0 to +70	°C
Temperature	Range		
Operating	Industrial Temperature	-40 to +85	°C
Temperature	Range		

NOTES:

 Stresses greater than those listed under ABSOLUTE MAXIMUM RATINGS may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect reliability.

The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.

 The maximum package power dissipation is calculated using a junction temperature of 150°C and a board trace length of 750 mils.

APPLICATIONS:

- SDRAM
- Telecom
- Datacom
- PC Motherboards/Workstations
- Critical Path Delay Designs

PIN DESCRIPTION

Pin Name	Pin Number	Туре	Functional Description	
REF	1	IN	Input reference clock, 5 Volt tolerant input	
CLK2 ⁽¹⁾	2	Out	Output clock	
CLK1 ⁽¹⁾	3	Out	Output clock	
GND	4	Ground	Ground	
CLK3 ⁽¹⁾	5	Out	Output clock	
Vdd	6	PWR	3.3V Supply	
CLK4 ⁽¹⁾	7	Out	Output clock	
CLKOUT ⁽¹⁾	8	Out	Output clock, internal feedback on this pin	

NOTES:

1. Weak pull down on all outputs.

OPERATING CONDITIONS-COMMERCIAL

Symbol	Parameter		Max.	Unit
Vdd	Supply Voltage		3.6	V
TA	A Operating Temperature (Ambient Temperature)		70	°C
CL	Load Capacitance < 100MHz		30	pF
	Load Capacitance 100MHz - 133MHz	_	10	
Cin	Input Capacitance	—	7	pF

DC ELECTRICAL CHARACTERISTICS-COMMERCIAL

Symbol	Parameter	(Conditions			Unit
VIL	Input LOW Voltage Level			—	0.8	V
Vін	Input HIGH Voltage Level			2	_	V
lı∟	Input LOW Current	VIN = 0V		—	50	μA
Ιн	Input HIGH Current	VIN = VDD		—	100	μA
Vol	Output LOW Voltage	Standard Drive	IOL = 8mA	—	0.4	V
		High Drive	IOL = 12mA (-1H)			
Vон	Output HIGH Voltage	Standard Drive	lон = -8mA	2.4	_	V
		High Drive	Іон = -12mA (-1H)			
IDD_PD	Power Down Current	REF = 0MHz	· ·	—	12	μA
IDD	Supply Current	Unloaded Outputs at 66.	.66MHz	—	32	mA

SWITCHING CHARACTERISTICS (2305-1) - COMMERCIAL^(1,2)

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
tı	Output Frequency	10pFLoad	10	—	133	MHz
		30pFLoad	10	—	100	
	Duty Cycle = $t_2 \div t_1$	Measured at 1.4V, Fout = 66.66MHz	40	50	60	%
t3	RiseTime	Measured between 0.8V and 2V	—	—	2.5	ns
t4	FallTime	Measured between 0.8V and 2V	—	—	2.5	ns
ts	Output to Output Skew	All outputs equally loaded	—	—	250	ps
t6	Delay, REF Rising Edge to CLKOUT Rising Edge	Measured at VDD/2	—	0	±350	ps
4	Device-to-Device Skew	Measured at VDD/2 on the CLKOUT pins of devices	—	0	700	ps
tJ	Cycle-to-Cycle Jitter, pk - pk	Measured at 66.66MHz, loaded outputs	—	—	200	ps
t LOCK	PLL Lock Time	Stable power supply, valid clock presented on REF pin		_	1	ms

NOTES:

1. REF Input has a threshold voltage of VDD/2.

2. All parameters specified with loaded outputs.

SWITCHING CHARACTERISTICS (2305-1H) - COMMERCIAL (1,2)

Symbol	Parameter	Conditions		Тур.	Max.	Unit
tı	Output Frequency	10pFLoad	10	—	133	MHz
		30pFLoad	10	—	100	
	Duty Cycle = $t_2 \div t_1$	Measured at 1.4V, FOUT = 66.66MHz	40	50	60	%
	Duty Cycle = $t_2 \div t_1$	Measured at 1.4V, FOUT <50MHz	45	50	55	%
ß	RiseTime	Measured between 0.8V and 2V	_	—	1.5	ns
t4	FallTime	Measured between 0.8V and 2V	_	_	1.5	ns
ъ	Output to Output Skew	All outputs equally loaded	_	—	250	ps
t6	Delay, REF Rising Edge to CLKOUT Rising Edge	Measured at VDD/2	—	0	±350	ps
4	Device-to-Device Skew	Measured at VDD/2 on the CLKOUT pins of devices	_	0	700	ps
t8	Output Slew Rate	Measured between 0.8V and 2V using Test Circuit #2	1	_	-	V/ns
tJ	Cycle-to-Cycle Jitter, pk - pk	Measured at 66.66MHz, loaded outputs	_	_	200	ps
t LOCK	PLL Lock Time	Stable power supply, valid clock presented on REF pin	_	_	1	ms

NOTES:

1. REF Input has a threshold voltage of VDD/2.

2. All parameters specified with loaded outputs.

OPERATING CONDITIONS-INDUSTRIAL

Symbol	Parameter	Min.	Max.	Unit
Vdd	Supply Voltage	3	3.6	V
TA	Operating Temperature (Ambient Temperature)	-40	+85	°C
CL	Load Capacitance < 100MHz	—	30	pF
	Load Capacitance 100MHz - 133MHz	—	10	
CIN	InputCapacitance	_	7	pF

DCELECTRICAL CHARACTERISTICS-INDUSTRIAL

Symbol	Parameter	C	conditions	Min.	Max.	Unit
VIL	Input LOW Voltage Level			—	0.8	V
Vih	Input HIGH Voltage Level			2	—	V
١L	Input LOW Current	VIN = 0V		—	50	μA
Ін	Input HIGH Current	VIN = VDD		—	100	μA
Vol	Output LOW Voltage	Standard Drive	IOL = 8mA	—	0.4	V
		High Drive	IoL = 12mA (-1H)			
Vон	Output HIGH Voltage	Standard Drive	Iон = -8mA	2.4	_	V
		High Drive	Іон = -12mA (-1H)			
IDD_PD	Power Down Current	REF = 0MHz		—	25	μA
ldd	Supply Current	Unloaded Outputs at 66.	66MHz	—	35	mA

SWITCHING CHARACTERISTICS (2305-1)-INDUSTRIAL

Symbol	Parameter	Conditions		Тур.	Max.	Unit
tı	Output Frequency	10pFLoad	10	—	133	MHz
		30pFLoad	10	—	100]
	Duty Cycle = $t_2 \div t_1$	Measured at 1.4V, FOUT = 66.66MHz	40	50	60	%
t3	RiseTime	Measured between 0.8V and 2V	_	—	2.5	ns
t4	FallTime	Measured between 0.8V and 2V	_	—	2.5	ns
ts	Output to Output Skew	All outputs equally loaded	_	—	250	ps
t6	Delay, REF Rising Edge to CLKOUT Rising Edge	Measured at VDD/2		0	±350	ps
4	Device-to-Device Skew	Measured at VDD/2 on the CLKOUT pins of devices	_	0	700	ps
tJ	Cycle-to-Cycle Jitter, pk - pk	Measured at 66.66MHz, loaded outputs	_	_	200	ps
t LOCK	PLL Lock Time	Stable power supply, valid clock presented on REF pin	_	_	1	ms

NOTES:

1. REF Input has a threshold voltage of VDD/2.

2. All parameters specified with loaded outputs.

SWITCHING CHARACTERISTICS (2305-1H) - INDUSTRIAL (1,2)

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
tı	Output Frequency	10pFLoad	10	—	133	MHz
		30pFLoad	10	_	100	
	Duty Cycle = t2 ÷ t1	Measured at 1.4V, FOUT = 66.66MHz	40	50	60	%
	Duty Cycle = $t_2 \div t_1$	Measured at 1.4V, FOUT <50MHz	45	50	55	%
t3	RiseTime	Measured between 0.8V and 2V		—	1.5	ns
t4	FallTime	Measured between 0.8V and 2V	_	—	1.5	ns
ts	Output to Output Skew	All outputs equally loaded	—	—	250	ps
t6	Delay, REF Rising Edge to CLKOUT Rising Edge	Measured at VDD/2		0	±350	ps
ħ	Device-to-Device Skew	Measured at VDD/2 on the CLKOUT pins of devices	_	0	700	ps
t8	Output Slew Rate	Measured between 0.8V and 2V using Test Circuit #2	1	_	_	V/ns
tJ	Cycle-to-Cycle Jitter, pk - pk	Measured at 66.66MHz, loaded outputs	_	_	200	ps
t LOCK	PLL Lock Time	Stable power supply, valid clock presented on REF pin	_	_	1	ms

NOTES:

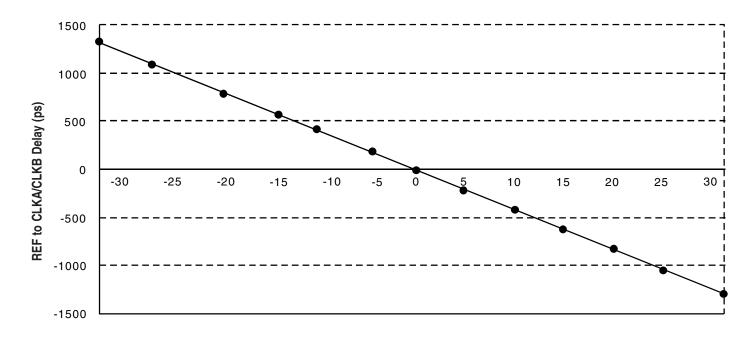
1. REF Input has a threshold voltage of VDD/2.

2. All parameters specified with loaded outputs.

ZERO DELAY AND SKEW CONTROL

All outputs should be uniformly loaded in order to achieve Zero I/O Delay. Since the CLKOUT pin is the internal feedback for the PLL, its relative loading can affect and adjust the input/output delay. The Output Load Difference diagram illustrates the PLL's relative loading with respect to the other outputs that can adjust the Input-Output (I/O) Delay.

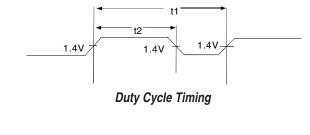
For designs utilizing zero I/O Delay, all outputs including CLKOUT must be equally loaded. Even if the output is not used, it must have a capacitive load equal to that on the other outputs in order to obtain true zero I/O Delay. If I/O Delay adjustments are needed, use the Output Load Difference diagram to calculate loading differences between the CLKOUT pin and other outputs. For zero output-to-output skew, all outputs must be loaded equally.

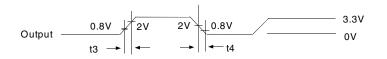


REF TO CLKA/CLKB RELAY vs. OUTPUT LOAD DIFFERENCE BETWEEN CLKOUT PIN AND CLKA/CLKB PINS

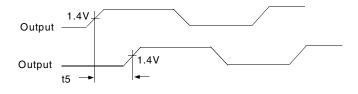
OUTPUT LOAD DIFFERENCE BETWEEN CLKOUT PIN AND CLKA/CLKB PINS (pF)

SWITCHING WAVEFORMS

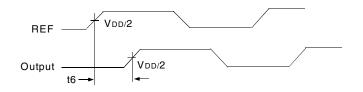




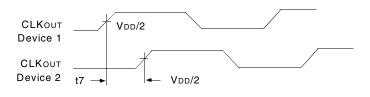
All Outputs Rise/Fall Time



Output to Output Skew

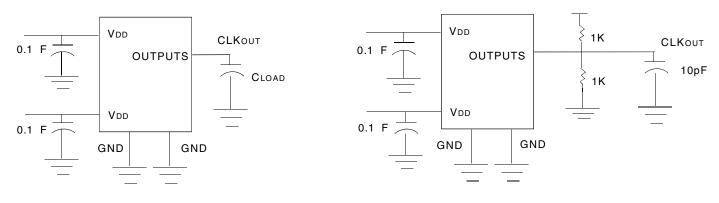


Input to Output Propagation Delay





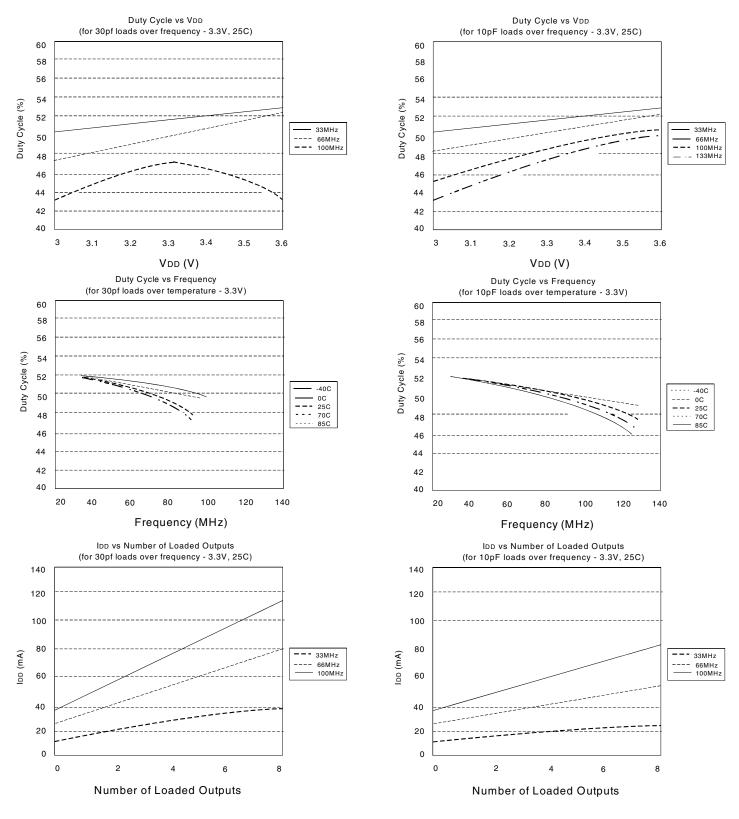
TEST CIRCUITS



Test Circuit 1 (all Parameters Except t8)

Test Circuit 2 (t8, Output Slew Rate On -1H Devices)

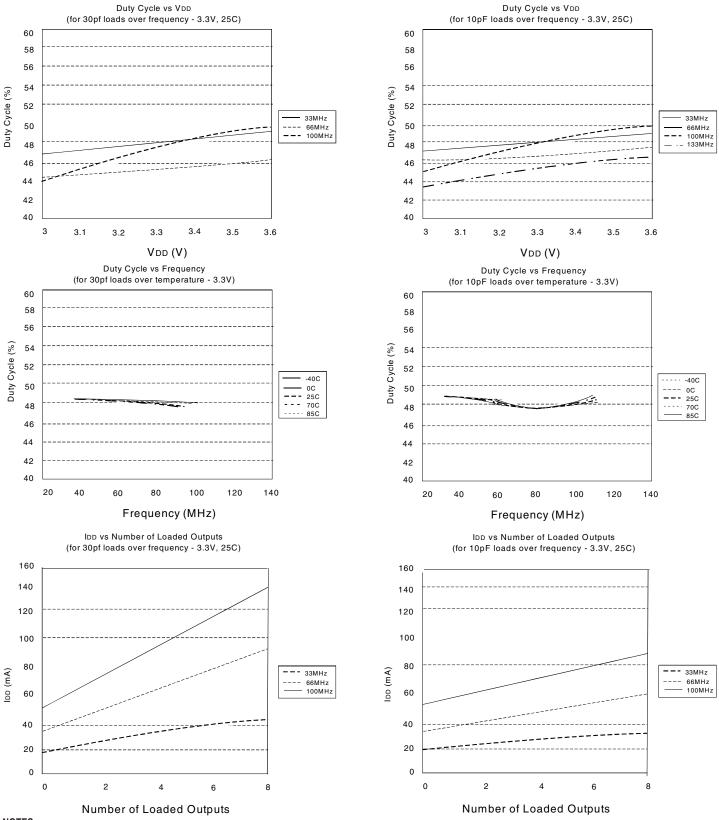
TYPICAL DUTY CYCLE⁽¹⁾ AND IDD TRENDS⁽²⁾ FOR IDT2305-1



NOTES:

- 1. Duty Cycle is taken from typical chip measured at 1.4V.
- 2. IDD data is calculated from IDD = ICORE + nCVf, where ICORE is the unloaded current. (n = Number of outputs; C = Capacitance load per output (F); V = Supply Voltage (V); f = Frequency (Hz))

TYPICAL DUTY CYCLE⁽¹⁾ AND IDD TRENDS⁽²⁾ FOR IDT2305-1H

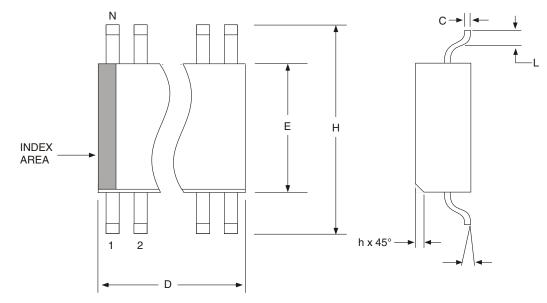


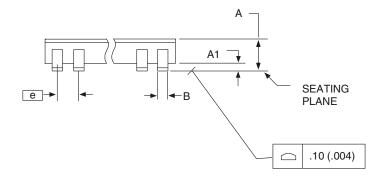
NOTES:

1. Duty Cycle is taken from typical chip measured at 1.4V.

 IDD data is calculated from IDD = ICORE + nCVf, where ICORE is the unloaded current. (n = Number of outputs; C = Capacitance load per output (F); V = Supply Voltage (V); f = Frequency (Hz))

PACKAGE OUTLINE AND PACKAGE DIMENSIONS-SOIC





150 mil (Narrow Body) SOIC

SYMBOL		meters IMENSIONS	In Inches ⁽¹⁾ COMMON DIMENSIONS			
	MIN	MAX	MIN	MAX		
А	1.35	1.75	.0532	.0688		
A1	0.10	0.25	.0040	.0098		
В	0.33	0.51	.0130	.0200		
С	0.19	0.25	.0075	.0098		
D	SEE VAF	SEE VARIATIONS		IATIONS		
E	3.80	4.00	.1497	.1574		
е	1.27	BASIC	0.050	BASIC		
н	5.80	6.20	.2284	.2440		
h	0.25	0.50	.010	.020		
L	0.40	1.27	.016 .050			
N	SEE VARIATIONS		SEE VARIATIONS			
	0°	8°	0°	8°		

VARIATIONS

N	D (r	nm)	D (inch) ⁽¹⁾		
IN	MIN	МАХ	MIN	МАХ	
8	4.80	5.00	.1890	.1968	
14	8.55	8.75	.3367	.3444	
16	9.80	10.00	.3859	.3937	

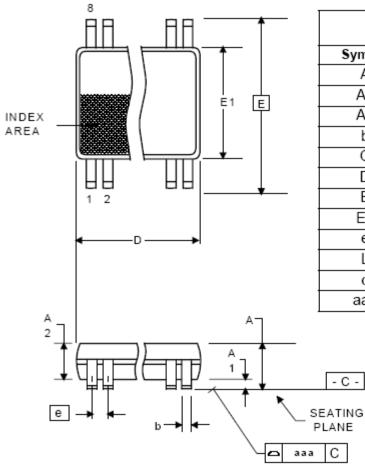
NOTE:

1. For reference only. Controlling dimensions are in mm.

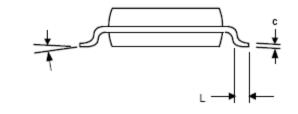
NOTE:

1. For reference only. Controlling dimensions are in mm.

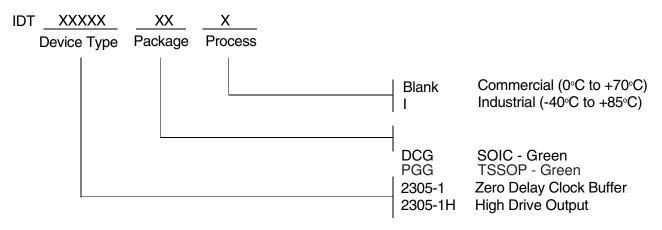
PACKAGE OUTLINE AND PACKAGE DIMENSIONS-TSSOP



	Millimeters		Inches	
Symbol	Min	Max	Min	Мах
А		1.20		0.047
A1	0.05	0.15	0.002	0.006
A2	0.80	1.05	0.032	0.041
b	0.19	0.30	0.007	0.012
С	0.09	0.20	0.0035	0.008
D	2.90	3.10	0.114	0.122
E	6.40 BASIC		0.252 BASIC	
E1	4.30	4.50	0.169	0.177
е	0.65 Basic		0.0256 Basic	
L	0.45	0.75	0.018	0.030
α	0°	8°	0°	8°
aaa	-	0.10	-	0.004



ORDERING INFORMATION



Ordering Code	Package Type	Operating Range
2305-1DCG8 (tape and reel)	8-Pin SOIC	Commercial
2305-1DCG	8-Pin SOIC	Commercial
2305-1DCGI8 (tape and reel)	8-Pin SOIC	Industrial
2305-1DCGI	8-Pin SOIC	Industrial
2305-1HDCG	8-Pin SOIC	Commercial
2305-1HDCG8 (tape and reel)	8-Pin SOIC	Commercial
2305-1HDCGI	8-Pin SOIC	Industrial
2305-1HDCGI8 (tape and reel)	8-Pin SOIC	Industrial
2305-1PGGI	8-Pin TSSOP	Industrial
2305-1PGG	8-Pin TSSOP	Commercial

(G=Lead-free, RoHS compliant)



CORPORATE HEADQUARTERS 6024 Silver Creek Valley Road San Jose, CA 95138

for SALES:

800-345-7015 or 408-284-8200 fax: 408-284-2775 www.idt.com for Tech Support: clockhelp@idt.com